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Handcrafted Solutions For A High-Tech World

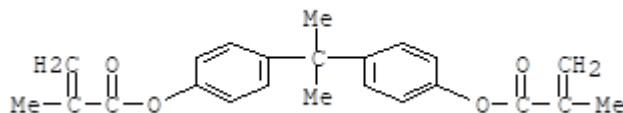
## Bisphenol A Dimethacrylate (BDMA)

**FP code 5040**

### General

Bisphenol-a-dimethacrylate is a high purity, curable resin suitable for the production of food packaging material as well as dental applications.

### Chemical structure



### Product information

|                    |  |
|--------------------|--|
| CHEMICAL NAME:     | 4,4'-Isopropylidenediphenol dimethacrylate     |
| TRADE NAMES:       | BDMA   |
| CAS NO.            | 3253-39-2                                      |
| HRI CODE:          | FP5040   |
| MOLECULAR FORMULA: | C <sub>23</sub> H <sub>24</sub> O <sub>4</sub> |
| MOLECULAR WEIGHT:  | 364  |
| REGISTRATIONS:     | AICS, DSL, EINECS, TSCA                        |
| SHELF LIFE:        | 6 months when stored indoor at 25(+/-5)        |

### Typical properties

|                  |               |
|------------------|---------------|
| APPEARANCE:      | White crystal |
| ASSAY            | 97.5 % min    |
| MELTING POINT    | 73 deg C      |
| COLOR (20% soln) | 20 apha       |

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## Safety and Handling

BDMA should be handled in accordance with good industrial practice. Detailed information is provided in the SDS.

BDMA is sensitive to sunlight and heat and will polymerize with prolonged exposure to either.

NOTE: Intellectual property issues cover the use of this material in select applications.  
For additional information visit our website [www.hampfordresearch.com](http://www.hampfordresearch.com).

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